AMENDMENT TO THE CLAIMS

1. (Canceled)

2. (Currently Amended) The method according to claim 10, wherein when laid the ~~substrate~~ wafer (4) applies a constant pressure on the protective layer (5).

3. (Currently Amended) The method according to claim 2, wherein a pressure medium is applied to a side of the ~~substrate~~ wafer (4) remote from the protective layer (5).

Claims 4-7 (Canceled)

8. (Previously Presented) The method according to claim 6, wherein the portion (8) is one of circular, oval and polygonal in cross-section when viewed from above.

9. (Currently Amended) The method according to claim 10, wherein a pressure medium is applied to a side of the ~~substrate~~ wafer (4) remote from the protective layer (5).

10. (Currently Amended) A method for applying a thin-walled, ~~flat substrate~~ planar semiconductor wafer to [[an]] a planar assembly carrier (6) with a protective layer (5), the improvement comprising:

with respect to the protective layer (5), arranging the ~~substrate~~ wafer at a spacing and curved in a convex manner, contacting the protective layer (5) with the ~~substrate~~ wafer (4), and laying the ~~substrate~~ wafer (4) over the protective layer (5) from a contact point towards an edge of the ~~substrate~~ wafer, and the ~~substrate~~ wafer being arched and detached from a carrying body (2) by controlling a pressure of a medium in a cavity between the ~~substrate~~ wafer (4) and the carrying body (2);

the carrying body (2) moveable relative to the assembly carrier (6) and including a planar portion (8) facing the protective layer (5) and carrying the ~~substrate~~ wafer (4), the portion (8) having a plurality of flow apertures (3, 7) for accommodating the pressure medium, the flow apertures (3, 7) including at least one centrally formed duct (7) configured as an overpressure line for arching the wafer (4)

and circumferential grooves (3) configured as negative pressure lines for releasably attaching the wafer (4) at the carrying body (2).

11. (Canceled)

12. (Previously Presented) The method according to claim 10, wherein the portion (8) is one of circular, oval and polygonal in cross-section when viewed from above.

Claims 13-23 (Canceled)